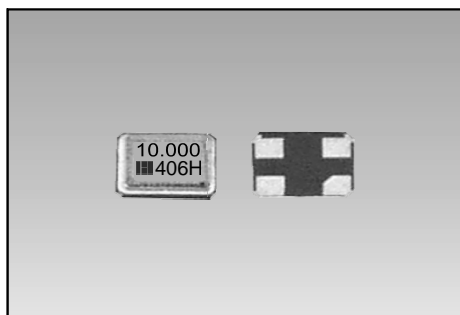


• HCX-5SB Series 5.0X3.2X0.90 mm



FEATURES

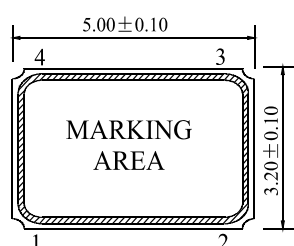
- Compact and thin (5.0X3.2X0.90mm max.)
- Prepared frequencies can meet most of bluetooth chipsets
- Excellent heat resistance and shock resistance.
- Products that are lead-free. These can meet the requirement of re-flow profiling using lead-free solder

Electrical Specifications

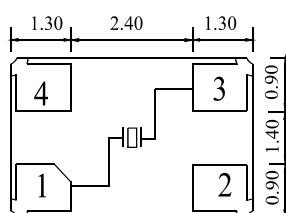
Item	Type	HCX-5SB				
Frequency Range	F0	8 to 9.999MHz	10 to 19.999MHz	20 to 29.999MHz	30 to 47.999MHz	48 to 80.000MHz
Mode of Vibration		Fundamental				3 rd Overtone
Load Capacitance	CL	10pF to Series				
Frequency Tolerance	$\Delta F/F_0$	$\pm 10\text{ppm}, \pm 30\text{ppm}, \pm 50\text{ppm}(\text{At } 25^\circ\text{C})$				
Equivalent Series Resistance	ESR	100 Ω max.	80 Ω max.	70 Ω max.	50 Ω max.	70 Ω max.
Temperature Stability	TC	$\pm 10\text{ppm}, \pm 30\text{ppm}, \pm 50\text{ppm}(\text{Refer to } 25^\circ\text{C})$				
Operating Temperature Range	T _{OPR}	$-20\sim+70^\circ\text{C}, -30\sim+85^\circ\text{C}$ Option				
Storage Temperature Range	T _{STG}	$-55\sim+125^\circ\text{C}$				
Shunt Capacitance	C0	7pF max.				
Insulator Resistance	IR	500M Ω min. (At 100V _{DC})				
Drive Level	DL	100 μW (300 μW max.)				
Aging	Fa	$\pm 2\text{ppm}$ max. (At 25 $^\circ\text{C}$, First year)				
Packing Unit		1000pcs/reel				

***Please contact us for inquiries regarding other Specifications*

Mechanical Dimensions(mm)



Top View



Recommended Solder Pattern

